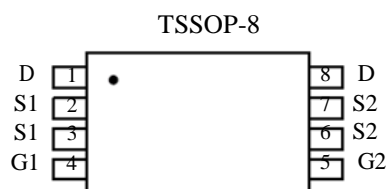


Dual N-Channel High Density Trench MOSFET

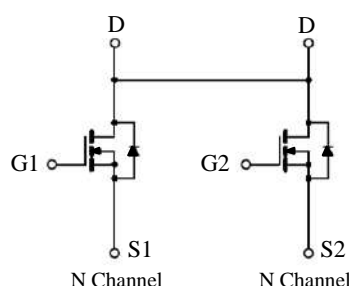
Features:

- Super high dense cell trench design for low $R_{DS(on)}$.
- Rugged and reliable.
- Ideal for Li ion battery pack application.



PRODUCT SUMMARY

V_{DSS}	I_D	$R_{DS(on)}$ (m Ω) Max
20V	6A	27 @ $V_{GS} = 4V$
	5.2A	38 @ $V_{GS} = 2.5V$



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 8	V
Drain Current-Continuous ^a @ $T_A = 25^\circ C$ -Pulse ^b	I_D	6	A
	I_{DM}	24	A
Drain-Source Diode Forward Current ^a	I_S	1.7	A
Maximum Power Dissipation ^a	P_D	$T_A = 25^\circ C$	1.5
		$T_A = 75^\circ C$	0.96
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to 150	$^\circ C$

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient ^a	R_{thJA}	83	$^\circ C/W$
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Note :

a. Surface Mounted on FR4 Board , $t \leq 10sec$.

b. Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS (T_A = 25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V , I _D = 250uA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20V , V _{GS} = 0V			1	uA
Gate-Body Leakage	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±100	nA
ON CHARACTERISTICS^b						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	0.5	0.9	1.5	V
Drain-Source On-State Resistance	R _{Ds(on)}	V _{GS} = 4V , I _D = 6A		23	27	mΩ
		V _{GS} = 2.5V , I _D = 5.2A		30	38	
DRAIN-SOURCE DIODE CHARACTERISTICS^b						
Diode Forward Voltage	V _{SD}	V _{GS} = 0V , I _S = 1.7A			1.2	V
DYNAMIC CHARACTERISTICS^c						
Input Capacitance	C _{ISS}	V _{DS} = 8V , V _{GS} = 0V f = 1.0MHz		522		pF
Output Capacitance	C _{OSS}			124		pF
Reverse Transfer Capacitance	C _{RSS}			148		pF
SWITCHING CHARACTERISTICS^c						
Turn-On Delay Time	t _{D(ON)}	V _{DD} = 10V , I _D = 1A		10		ns
Rise Time	t _r		V _{GEN} = 4.5V		8.2	
Turn-Off Delay Time	t _{D(OFF)}	R _L = 10 Ω		2.5		ns
Fall Time	t _f	R _{GEN} = 6 Ω		6		ns
Total Gate Charge	Q _g	V _{DS} = 10V , I _D = 3A V _{GS} = 4.5V		6.1		nC
Gate-Source Charge	Q _{gs}			1.7		nC
Gate-Drain Charge	Q _{gd}			1.4		nC

Note :
 b. Pulse Test : Pulse width ≤ 300us , Duty Cycle ≤ 2% .
 c. Guaranteed by design , not subject to production testing .

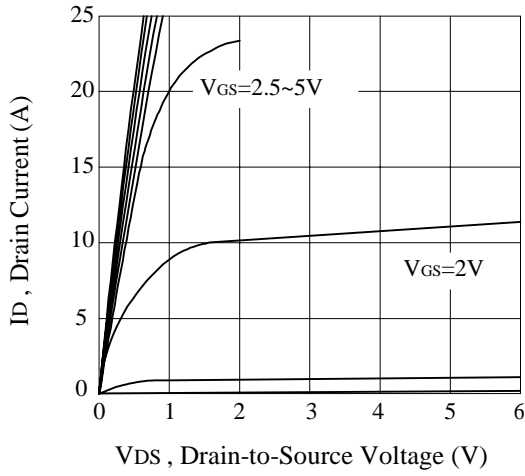


Figure 1. Output Characteristics

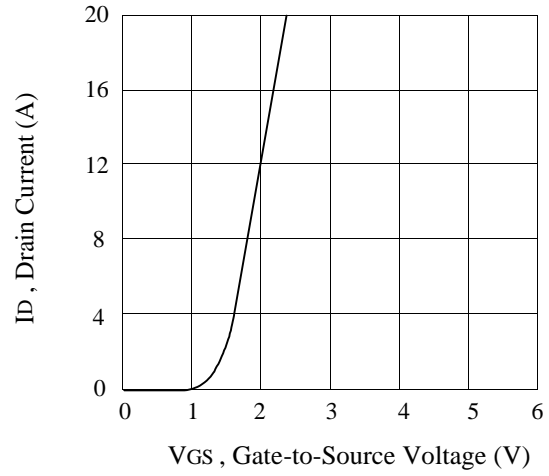


Figure 2. Transfer Characteristics

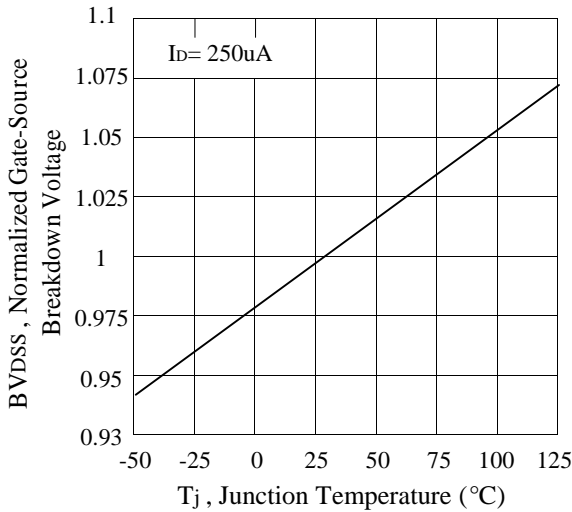


Figure 3. Breakdown Voltage Variation with Temperature

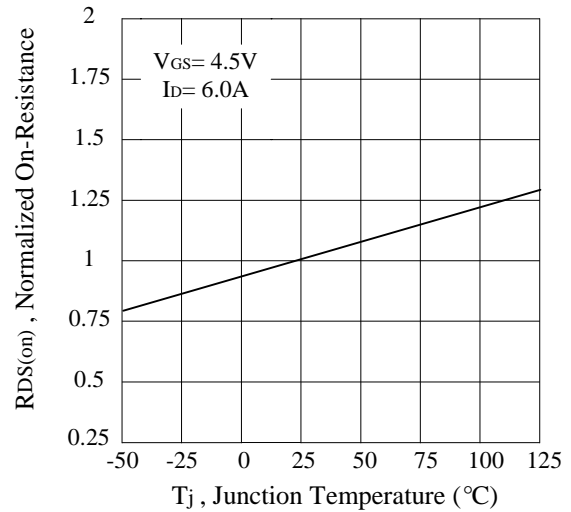


Figure 4. On-Resistance Variation with Temperature

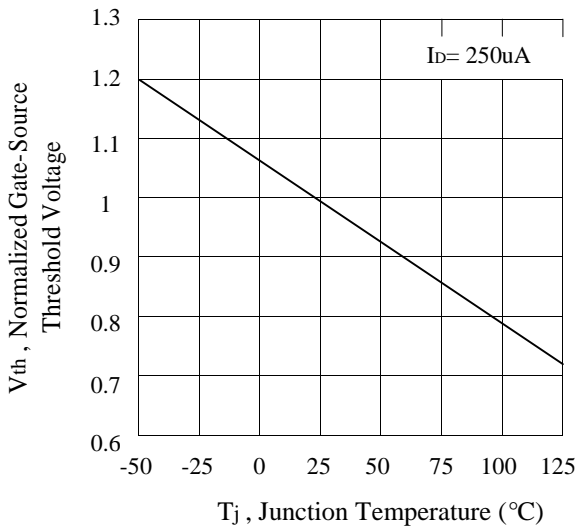


Figure 5. Gate Threshold Variation with Temperature

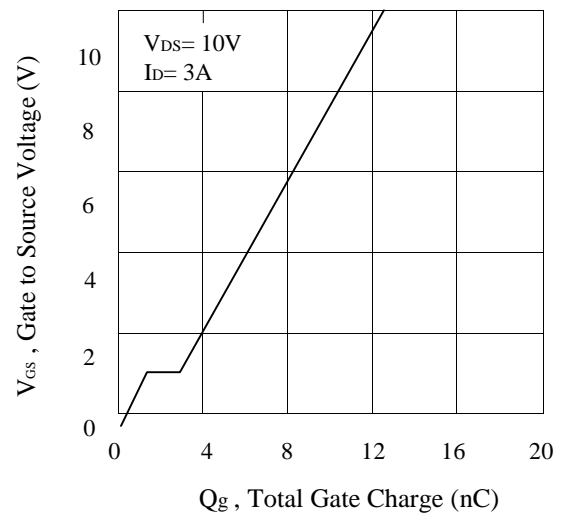
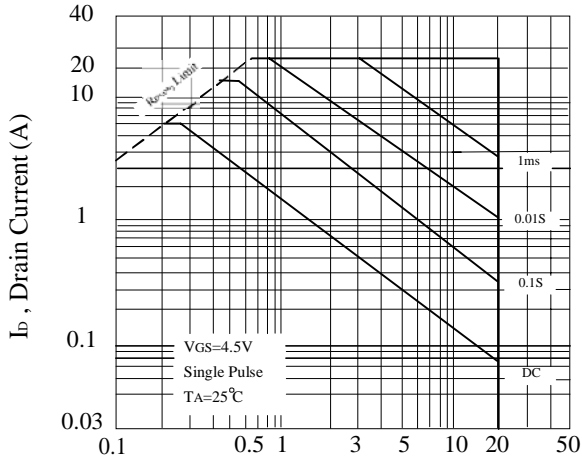
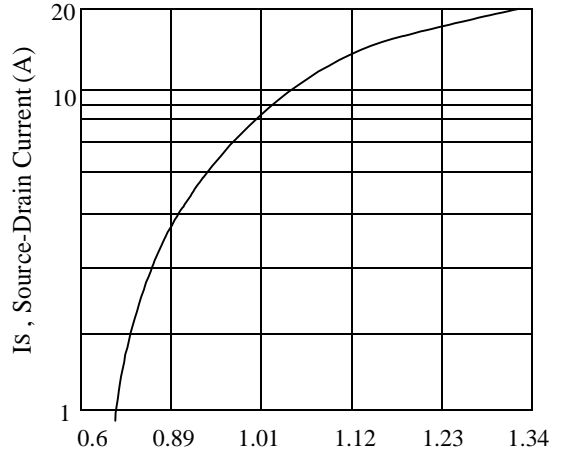


Figure 6. Gate Charge



VDS, Drain-Source Voltage (V)
Figure 7. Maximum Safe Operating Area



VSD, Body Diode Forward Voltage (V) **Figure 8.**
 Body Diode Forward Voltage Variation with Source Current

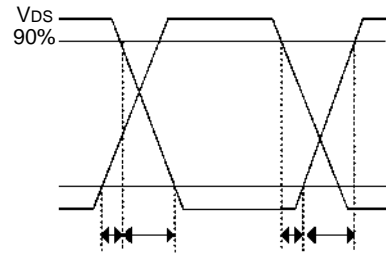
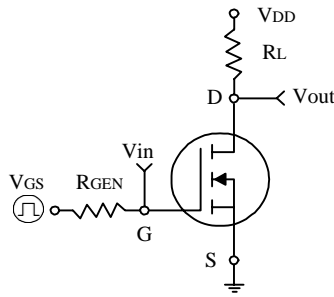


Figure 9. Switching Test Circuit and Switching Waveforms

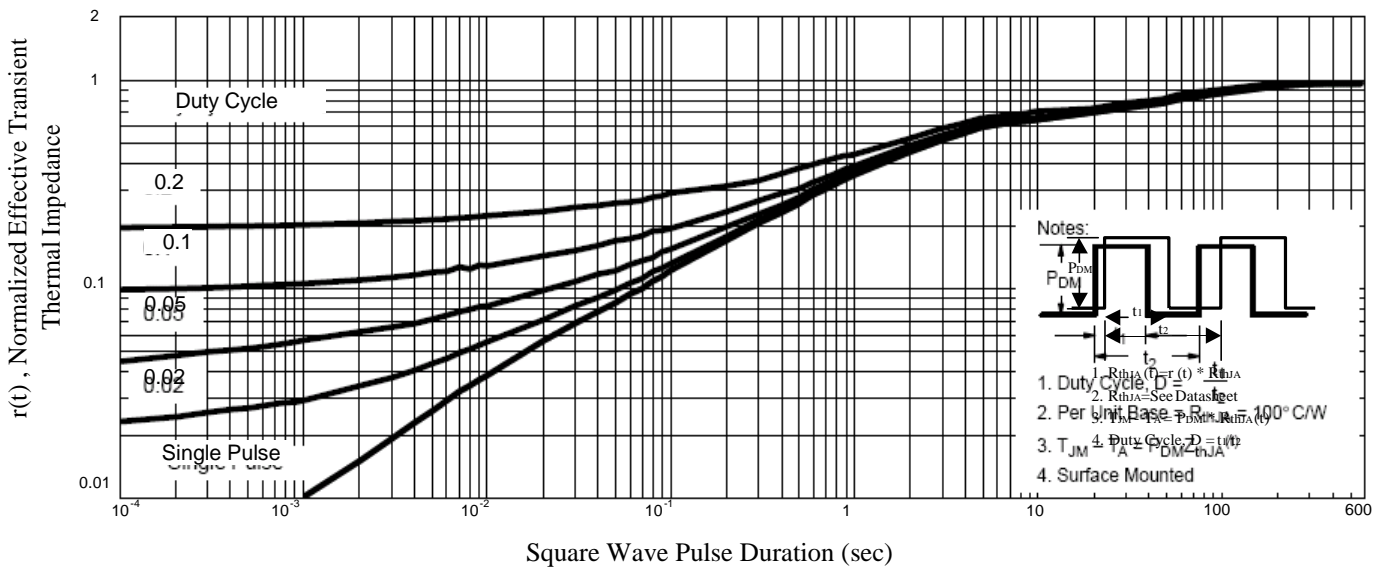


Figure 10. Normalized Thermal Transient Impedance Curve